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HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP,
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SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR,
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(54) Title: ELECTRONIC MODULE ASSEMBLY FOR FILTERED FEEDTHROUGHS

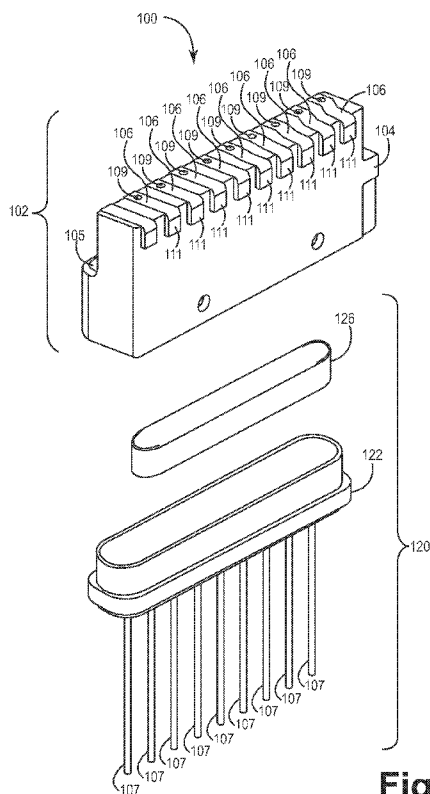


Fig. 4A

(57) Abstract: An electronic module assembly (EMA) for an implantable medical device is disclosed. The EMA comprises a non-conductive block having a top side, a bottom side, a front side and a back side. A plurality of conductive strips are coupled to the non-conductive block. Each conductive strip possesses a front side and a back side. The back side of each conductive strip is directly connected or embedded into the surfaces of the front side, the top side and the back side of the non-conductive block.



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ELECTRONIC MODULE ASSEMBLY FOR FILTERED FEEDTHROUGHS

TECHNICAL FIELD

5 The present disclosure relates generally to implantable medical devices, and, more particularly, to an electronic module assembly that includes contact pads for connecting feedthrough pins to a hybrid assembly.

BACKGROUND

10 Implantable medical devices (IMDs) typically include a housing that encloses a variety of internal components, and protects the components from an implanted environment. For example, within the human body, the housing is sealed to prevent introduction of fluids or moisture to the internal components. In many cases, the implantable medical device includes external components that extend outside of the
15 housing and communicate with the internal components.

 One example is an implantable cardioverter/defibrillator (ICD), which includes an internal battery, at least one charging capacitor, and electronic circuitry. The electronic circuitry typically is coupled to pacing and/or diagnostic leads that extend outside of the device housing for positioning within or near the targeted tissue such as the heart. To
20 protect internal components while permitting electrical connections with external components, the ICD includes a connector module connected to a filtered feedthrough electronic module assembly (FFEMA). The connector module is electrically connected to circuitry inside a sealed case of the implantable medical device through one or more feedthrough pins extending from the FFEMA. FFEMA comprises an electronic module
25 assembly (EMA) connected to a feedthrough assembly via laser welding of the feedthrough pins to the conductive strip on the EMA. The EMA is composed of an electronic module block with a set of conductive strips located solely at one end of the EMB. To ensure that a high quality EMB has been manufactured, a testing device with a set of pogo pins verifies that the conductive strips function properly. In some cases, the
30 pogo pins may contact the conductive strips more than once, which may remove a portion of a conductive plating on the conductive strips. A current is then passed through the pogo pins to test whether the conductive strips function. Pogo pins may scratch, nick or gouge

the gold/platinum plated surface of the conductive strips, which may not permit a reliable connection of the hybrid circuit to the EMB via laser ribbon bonding/wire bonding/parallel gap welding process to the conductive strip of the EMB .

Efforts to simplify or reduce the complexity, cost, and time of the manufacturing and assembly process can directly impact the cost of the implantable medical device for patients. Accordingly, more simple and cost-effective device assembly processes for implantable medical devices are desirable.

BRIEF DESCRIPTION OF THE DRAWINGS

The following drawings are illustrative of particular embodiments of the present invention and therefore do not limit the scope of the invention. The drawings are not to scale (unless so stated) and are intended for use in conjunction with the explanations in the following detailed description. Embodiments of the present invention will hereinafter be described in conjunction with the appended drawings, wherein like numerals denote like elements.

FIG. 1 is a conceptual schematic angled view of an implantable medical device (IMD) in which a medical electrical lead extends therefrom;

FIG. 2 is a schematic top view of the IMD depicted in **FIG. 1**;

FIG. 3A is a schematic interior view of one side of a housing to an IMD that includes a top side view of a filtered feedthrough electronic module assembly (FFEMA);

FIG. 3B is a schematic exterior view of the other side of a housing depicted in **FIG. 3A** to an IMD along with a back side view of a FFEMA;

FIG. 3C is a schematic cutaway view of the FFEMA depicted in **FIGs. 3A-3B**;

FIG. 4A is a schematic view of components of a FFEMA for the IMD depicted in **FIGs. 3A-3C**;

FIG. 4B is a schematic view of an assembled FFEMA for the IMD depicted in **FIGs. 3A-3B**;

FIG. 5A is a schematic view of a FFEMA for the IMD depicted in **FIGs. 3A-3B**;

FIG. 5B is a schematic view of a FFEMA for the IMD depicted in **FIGs. 3A-3B**;

FIG. 6 is an electronic module block of the FFEMA;

FIG. 7 is a top view of an electronic module block for the FFEMA; and

FIG. 8 depicts a flow diagram for forming an EMA.

5

DETAILED DESCRIPTION

The following description is merely exemplary in nature and is not intended to limit the present disclosure, application, or uses. The devices described herein include an exemplary number of leads, etc. One will understand that the components, including number and kind, may be varied without altering the scope of the disclosure. Also, devices according to various embodiments may be used in any appropriate diagnostic or treatment procedure, including a cardiac procedure.

With reference to **Fig. 1**, an implantable medical device (IMD) **20** can include implantable pacemakers, implantable cardioverter defibrillator (ICD) devices, cardiac resynchronization therapy defibrillator devices, neurostimulators, drug pumps or combinations thereof. Exemplary IMDs are commercially available as including one generally known to those skilled in the art, such as the Medtronic CONCERTO™, SENSIA™, VIRTUOSO™, RESTORE™, RESTORE ULTRA™, sold by Medtronic, Inc. of Minnesota. IMD **20** can include an implantable case, housing or body assembly **22**. Implantable case **22** can be formed of appropriate materials and include appropriate features, such as a hermetically sealed body wall **24a**. Body wall **24a** comprises substantially conductive material such as titanium.

Contained within or associated with case **22** can be a power device **25** such as one or more batteries and/or capacitors encased in housing or case body wall **24b**, a controller assembly **26**, and a connector body **27**. Controller assembly **26** can include a circuit board having a processor, memory, transmitter, receiver, and/or other appropriate portions. Connector body **27** can extend from or be integrated with case **22**. At its distal end, connector body **27** can include one or more ports **28a,b** that interconnects with one or more connector terminals **30a,b** of one or more lead assemblies **32a,b**. Exemplary connector bodies **27** can include IS-1 connectors, IS-4 connectors or other suitable

connectors. Lead assemblies **32a,b** generally include respective lead bodies **34a,b** each having a respective tip electrode **36a,b**. For example, the first lead assembly **32a** can include an active tip electrode **36a** and the second lead assembly can include a passive tip electrode **36b**.

5 At its distal end, connector body **27** is connected via set screws **29** to lead assemblies **32a,b**. Set screws **29** force lead assemblies **32a,b** in place to form an electrical connection via connector body **27**, which, at its proximal end, is connected to a filtered feedthrough electronic module assembly (FFEMA) **100**, as depicted in **FIGs. 3A-5B**. **FIG. 3A** depicts an interior side **40a** of housing **24a** whereas **FIG. 3B** shows the flip side or exterior side **40b** of the same side of housing **24a**. FFEMA **100** electrically connects circuitry, such as a hybrid assembly **162** shown in **FIG. 3C**, located inside a sealed case of the IMD, to a connector body **27**, which connects with external components that extend outside of the housing **24a**. FFEMA **100** comprises an electronic module assembly (EMA) **102** connected to a feedthrough assembly **120**. The EMA **102** is composed of a
10 non-conductive block, referred to as an electronic module block (EMB) **104**, with a set of conductive strips **106** or conductive elements.

 EMB **104** is substantially L-shaped; however a variety of suitable shapes can be used. The EMB **104** includes a non-conductive body **102** formed of, for example, silicone, polyurethane and other suitable material. A number of openings or apertures **109**
15 are defined through the body **102** between top and bottom sides. The openings **109** are capable of accepting or receiving feedthrough pins **107** or conductors.

 EMB **104** includes a top side **128a**, a bottom side **128d**, a front side **128b** and a back side **128c**. Top side **128a**, shown in **Fig. 7**, possesses a flat or substantially flat surface.
20

25 A set of conductive strips **106** are electrically and mechanically coupled to the EMB **104** to form EMA **102**. In one or more embodiments, each conductive strip **106** possesses a front side and a back side. While the front side of each conductive strip **106** is exposed, the back side conductive strip **106** is directly connected or embedded into the surfaces of the front side **128b**, the top side **128a**, and the back side **128c**; however, the set
30 of conductive strips **106** are not directly placed on the surface of the bottom side **128d**. Each conductive strip **106** extends X distance from the top side **128a** of the EMB **104**

toward the back side **128c**. X ranges from about 0.5 millimeters (mm) to about 5.0mm. The width of each conductive strip **106** portion on the back side **128c** can range from about 5mm to about 25mm.

A pad **111** or portion of each conductive strip **106** on the back side **128c** is used for testing the quality of each conductive strip **106** to conduct current. Pad **111**, in one or more embodiments, is seamlessly and/or integrally formed as part of conductive strip **106**. In another embodiment, pad **111** can be connected as a separate component to conductive strip **106** through conventional means. Each portion of the conductive strip **106**, on the backside of the EMB **104**, comprises a thickness that ranges from about 0.5mm to about 2.0 mm. Each conductive strip **106** is comprised of titanium, gold, nickel or any combination thereof.

Feedthrough assembly **120**, depicted in **FIGs. 4A-4B**, is conventionally formed and connected to EMA **104** in order to form FFEMA **100**. Each multipolar feedthrough element **120** includes a feedthrough pins **107**, a ferrule **122**, a capacitive element **126**, an insulator member or element (not shown), and conductive material (not shown) (also referred to as a conductive element). An exemplary multipolar feedthrough element that shows the configuration of the insulator member and conductive material around the pin may be seen with respect to U.S. Patent Application No. 12/183,593, filed July 31, 2008 entitled "NOVEL CAPACITIVE ELEMENTS AND FILTERED FEEDTHROUGH ASSEMBLIES FOR IMPLANTABLE MEDICAL DEVICES", and assigned to the assignee of the present invention, the disclosure of which is incorporated by reference in its entirety herein.

Suitable materials for feedthrough members **107** and ferrule **122** can include titanium, niobium, platinum, platinum/iridium, molybdenum, zirconium, tantalum or alloys thereof. The insulator element can comprise an insulative material such as glass, ceramic or other suitable materials. The conductive material can be a conductive epoxy, a conductive polyimide, a conductive solder or other suitable materials. An exemplary conductive epoxy can be Ablebond 8700E commercially available from Ablestik Inc., located in Rancho Dominguez, CA; an exemplary conductive polyimide can include Ablebond 71-1 from Ablestik Inc., and exemplary conductive solders can be indium-based, tin-based, gold-based solder, and/or lead based.

The electrically grounded ferrule **122** holds or supports an array of feedthrough pins **107** extending through the ferrule **122**. A monolithic discoidal capacitor assembly **126** is positioned around at least some of the feedthrough pins **107**. The capacitor assembly **126** is held together by a monolithic body. The capacitor assembly **126** is electrically connected between a feedthrough pin **107** and ground (i.e., to the ferrule **122**) to provide low-pass electromagnetic interference (EMI) filtering. An EMA block **104** can be positioned over the feedthrough pin **107** and the discoidal capacitor assembly **126**. Feedthrough pins **107** pass through the holes **109** in the conductive strips **106** on the EMB **104**. Feedthrough pins **107** are then trimmed flush to the conductive strips **106** and laser welded such that the trimmed pins **107** make an electrical connection to the conductive strips **106**. Thereafter, as shown in **FIG. 3C**, a conductive ribbon **160** or weld connects one or more feedthrough pins **107** to one or more corresponding bond pads **166** on a hybrid assembly or circuit board **162**.

FIG. 8 depicts a method of forming an EMA **104**. At block **200**, a mold (not shown) is provided that is configured to form a non-conductive block or EMB **102** with a top side, a back side, a front side, and a bottom side. The mold possesses features that provide a surficial mirror image of EMB **102**. The first side of the mold forms the top side of the non-conductive block, the second side of the mold forms the back side of the non-conductive block, and the third side of the mold forms the front side of the mold. Non-conductive block does not conduct current. The front side is directly adjacent to the top side and the top side is directly adjacent to the back side of the non-conductive block. In one or more embodiments, a polymer such as silicone, polyurethane, polyetherimide, and/or poly ether ether ketone can be used to form EMB **102**. A 10-30% glass filled polyetherimide is commercially available under the tradename Ultem from General Electric located in New York. At block **210**, a plurality of conductive strips are placed in the mold at a first side, a second side and a third side of the mold. Each conductive strip is formed of titanium or nickel and plated and/or sputtered with gold and/or platinum to provide a low resistance path. At block **220**, a polymeric material such as silicone and/or polyurethane is introduced into the mold. At block **230**, the EMA is formed such that the non-conductive block has a top side, a back side, a front side, and a bottom side. Each conductive strip extends from the front side over the top side onto the back side of the non-conductive block.

After EMA **102** has been formed, EMA **102** is tested, for example, to ensure that conductive strips **106** properly function. An exemplary testing system may be seen with respect to U.S. Patent Application No. 11/236,369, filed September 27, 2005 entitled "Determination of Equivalent Series Resistance", and assigned to the assignee of the present invention, the disclosure of which is incorporated by reference in its entirety herein. The testing system described herein includes a testing fixture with a set of pogo pins. EMA **102**, the device under test, is secured beneath the test fixture's set of pogo pins. The pogo pins move toward the pads **111** of conductive strips **106** until contacting the pads **111**. A current is passed through each pogo pin through to pads **111**. If current passes through each conductive strip **106**, the conductive strips **102** of the EMA **102** pass its quality inspection for functionally being able to pass current. If one or more conductive strips **102** cannot pass current, the EMA **102** fails its quality inspection and is not used in the formation of a FFEMA for an IMD. Since the pogo pins no longer contact the conductive strips **106** on the top side **126b** of EMA **102**, the surface of the conductive strips **106** remains intact. By preventing any nicks or gouges associated with test probes to the surface of the conductive strips **106**, a pristine surface on the conductive strips **106** is maintained for subsequent processes such as laser ribbon bonding, wire bonding or other suitable operations. Additionally, it is more likely that EMA **102** will pass the quality inspection related to conducting current through the conductive strips **106**. In turn, the cost of an IMD is reduced for patients.

Although the present invention has been described in considerable detail with reference to certain disclosed embodiments, the disclosed embodiments are presented for purposes of illustration and not limitation and other embodiments of the invention are possible. It will be appreciated that various changes, adaptations, and modifications may be made without departing from the spirit of the invention and the scope of the appended claims. For example, while one method for forming EMB **104** involves the use of a mold, it should be appreciated that numerous methods may be used to form EMA **102** without a mold. For example, EMB **104** could be extruded or formed through any conventional means. Additionally, the conductive strips can be coupled to the EMB **104** through hot pressing each strip into EMB **104**, or using an adhesive to connect each strip to EMB **104**.

WHAT IS CLAIMED IS:

1. An implantable medical device (IMD) comprising:
a housing;
5 a connector module coupled to the housing;
a filtered feedthrough electronic module assembly (FFEMA) coupled to the connector module and to the housing, the FFEMA comprises:
a filtered feedthrough assembly that includes a set of feedthrough pins;
an electronic module assembly (EMA), the EMA comprises:
10 an electronic module block (EMB) having a top side, a bottom side, a front side and a back side;
a set of conductive strips correspondingly coupled to the set of feedthrough pins, wherein each conductive strip being directly coupled to the front side, the top side, and the back side of the EMB;
15 at least one conductive connector being coupled to at least one feedthrough pin and a hybrid assembly.
2. The IMD of claim 1, wherein each conductive strip extends from the top side of the EMB toward the back side from about 0.5 millimeters (mm) to about 5mm.
- 20 3. The IMD of claim 2, wherein each conductive strip seamlessly extending along surfaces of the front side, the top side, and the back side of the EMB.
4. The IMD of claim 3, wherein at least a portion of each conductive strip is exposed
25 at the front side of the EMB.
5. The IMD of claim 4, wherein each conductive strip being embedded into the front side, the top side and the backside of the EMB.
- 30 6. The IMD of claim 1, wherein each conductive strip, on the backside of the EMB, comprising a thickness that ranges from about 0.5mm to about 2 mm.

7. The IMD of claim 1, wherein each conductive strip being comprised of one of titanium, nickel, aluminum, copper, niobium, and tantalum.

8. The IMD of claim 7 wherein each conductive strip being plated with at least one of gold and platinum.

9. The IMD of claim 1, wherein the EMB comprises a polymer selected from the group consisting of silicone, polyurethane, and poly ether ether ketone or combinations thereof.

10. The IMD of claim 1, wherein the top side being directly adjacent to the back side and the front side of the EMB.

11. The IMD of claim 1, wherein each feedthrough pin being laser welded to each corresponding conductive strip.

12. The IMD of claim 1, wherein one of gold, platinum and copper introduced over at least one surface of at least one conductive strip to provide a low resistive path between the feedthrough pin and the hybrid assembly .

13. An electronic module assembly (EMA) for an implantable medical device, the EMA comprising:

a non-conductive block having a top side, a bottom side, a front side and a back side; and

a plurality of conductive strips coupled to the non-conductive block, each conductive strip having a front side and a back side, the back side of each conductive strip extends from the front side across the top side and over to back side of the non-conductive block.

14. The EMA of claim 13, wherein the front side of each conductive strip is exposed.

15. The EMA of claim 13, wherein each conductive strip extends from the top side of the non-conductive block toward the bottom side from about 0.5 millimeters (mm) to about 5mm.

5 16. A method of forming an EMA for an implantable medical device comprising:
providing a mold configured to form a non-conductive block with a top side, a
bottom side, a front side, and a bottom side;
placing a plurality of conductive strips at a first side, a second side and a third side
of the mold, the first side of the mold forms the top side of the non-conductive block, the
10 second side of the mold forms the back side of the non-conductive block, and the third
side of the mold forms the front side of the mold;
introducing a polymeric material into the mold; and
forming the EMA comprising the non-conductive block having a top side, a back
side, a front side, and a bottom side, each conductive strip extending seamlessly from the
15 front side over the top side onto the back side of the non-conductive block.

17. The method of claim 16, wherein a portion of each conductive strip that extends to the back side of the non-conductive block serves as a test pad for testing the conductivity of each conductive strip.

20 18. The method of claim 16, wherein the front side is directly adjacent to the top side and the top side is directly adjacent to the back side of the non-conductive block.

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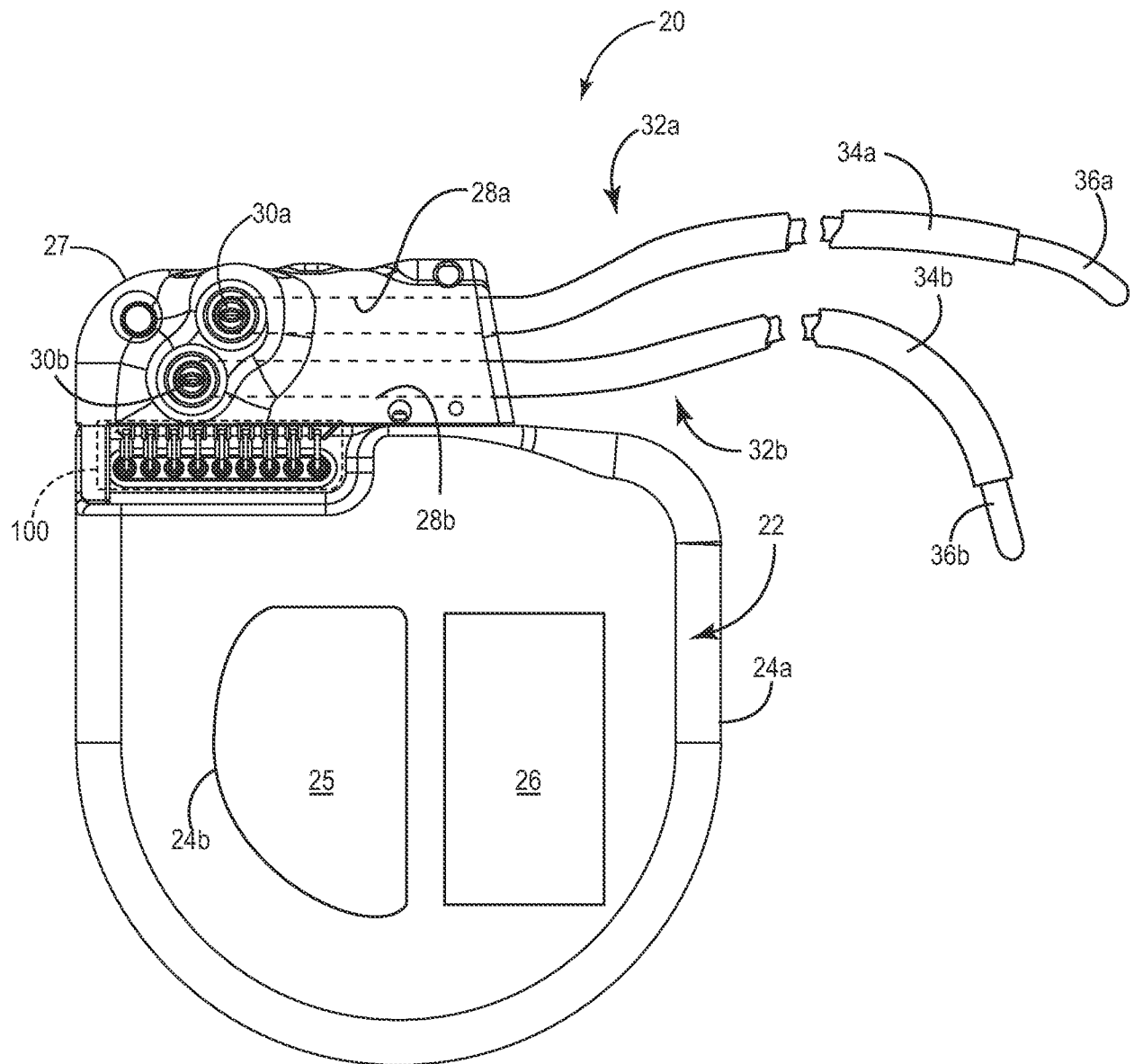


Fig. 1

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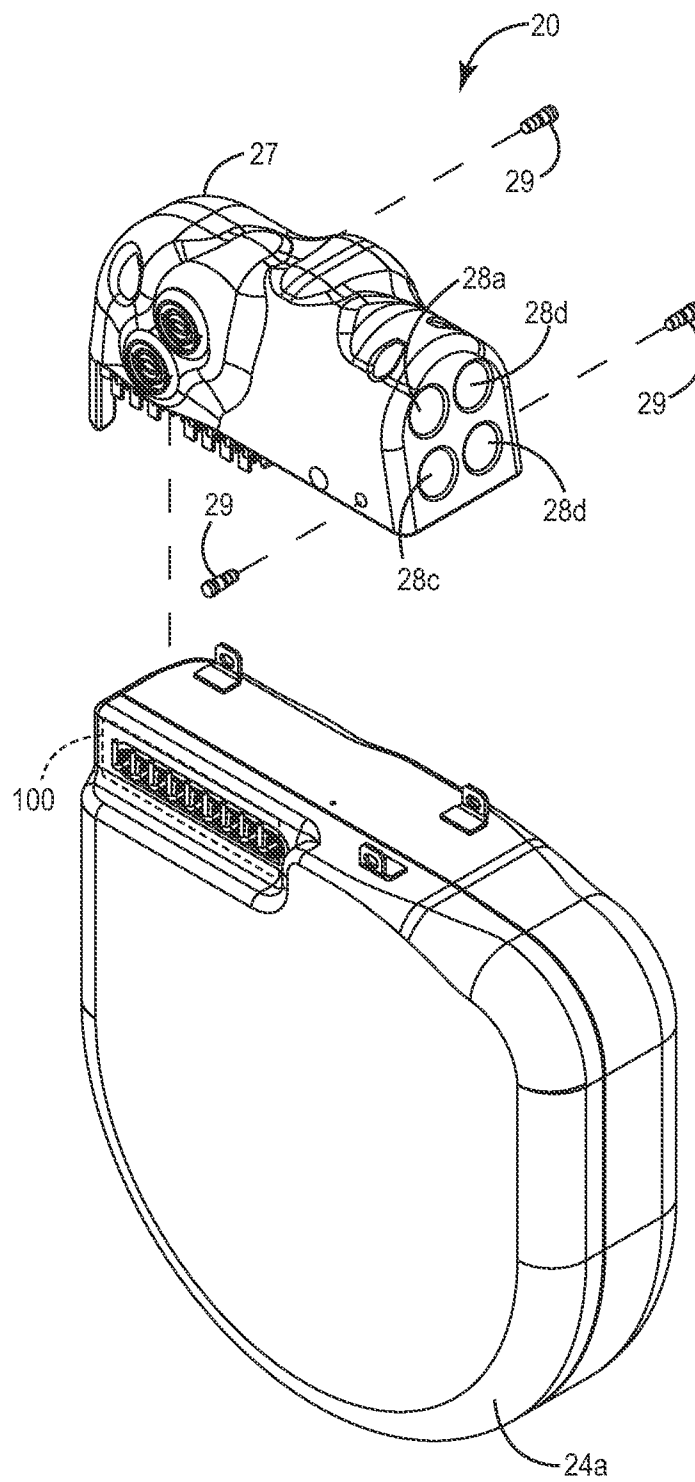


Fig. 2

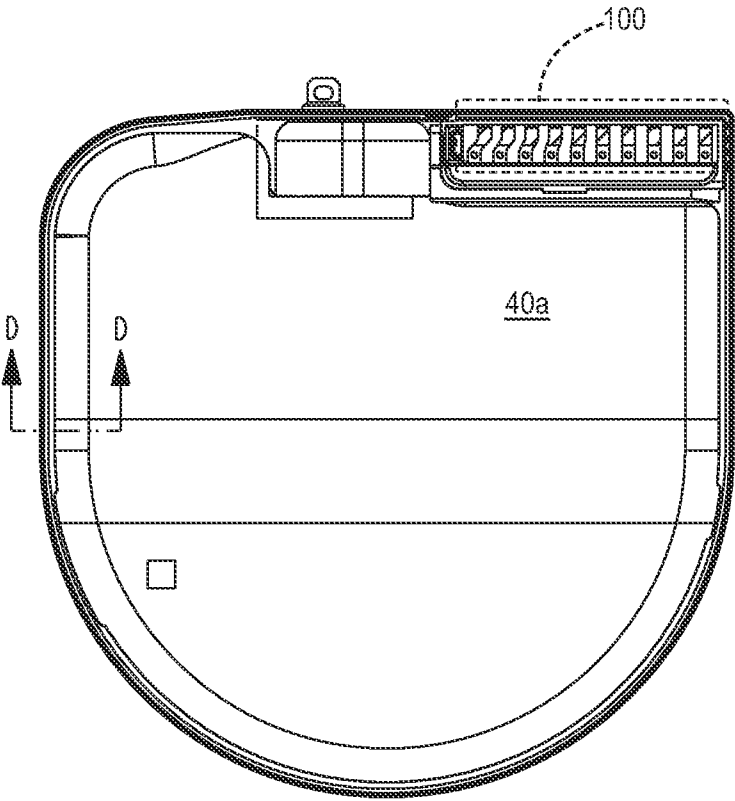


Fig. 3A

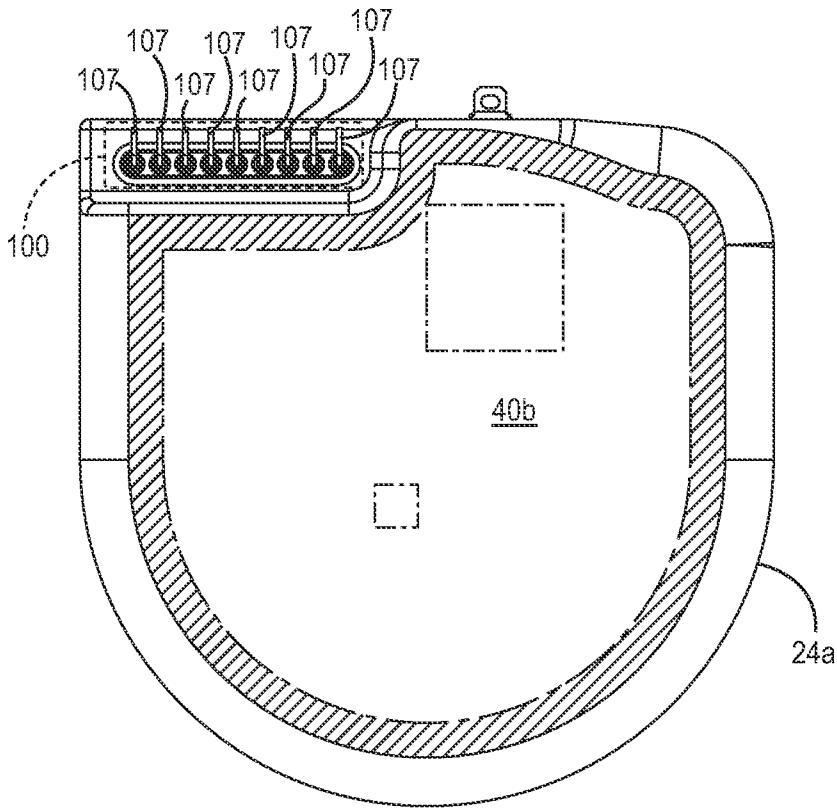


Fig. 3B

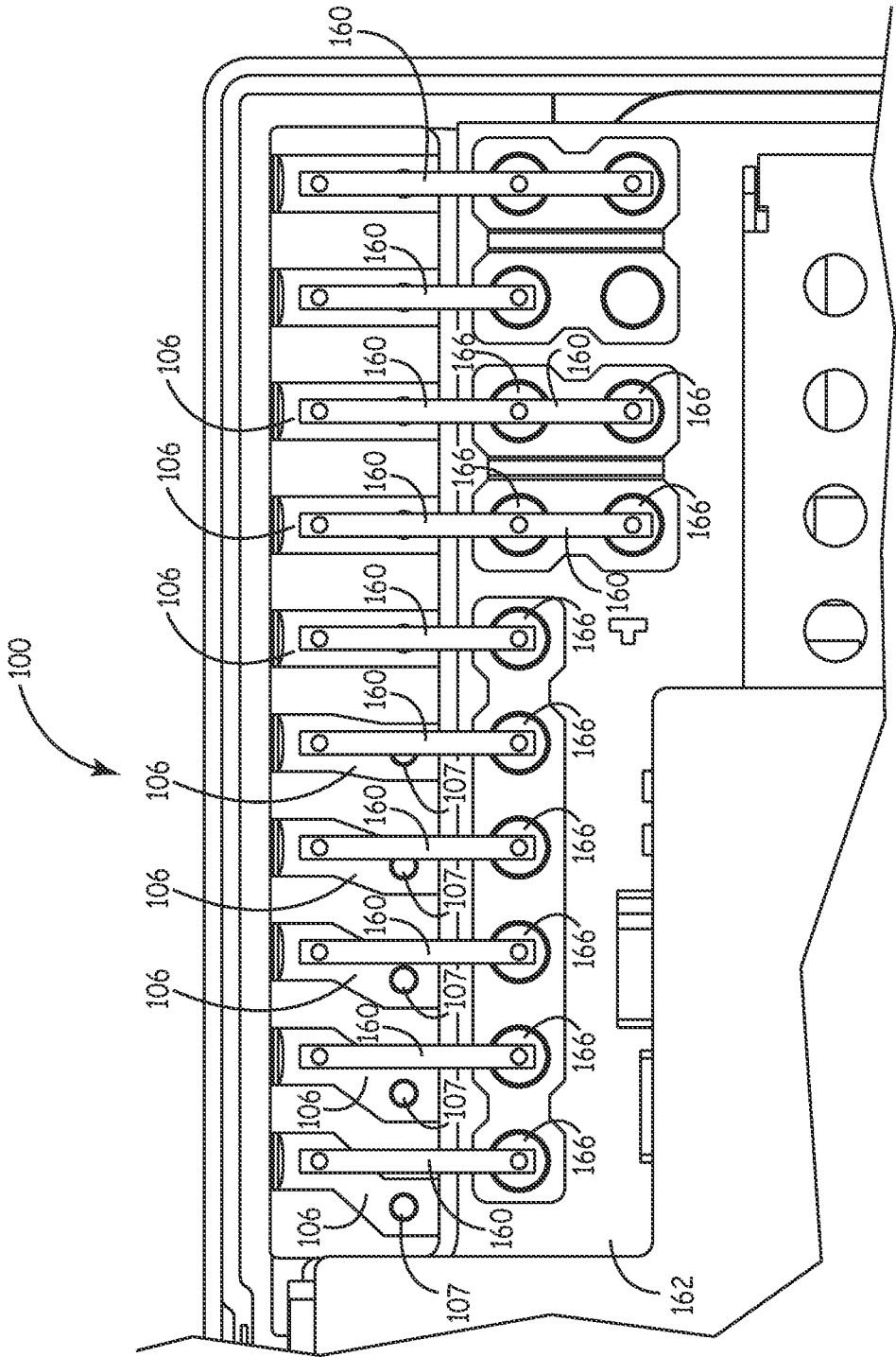
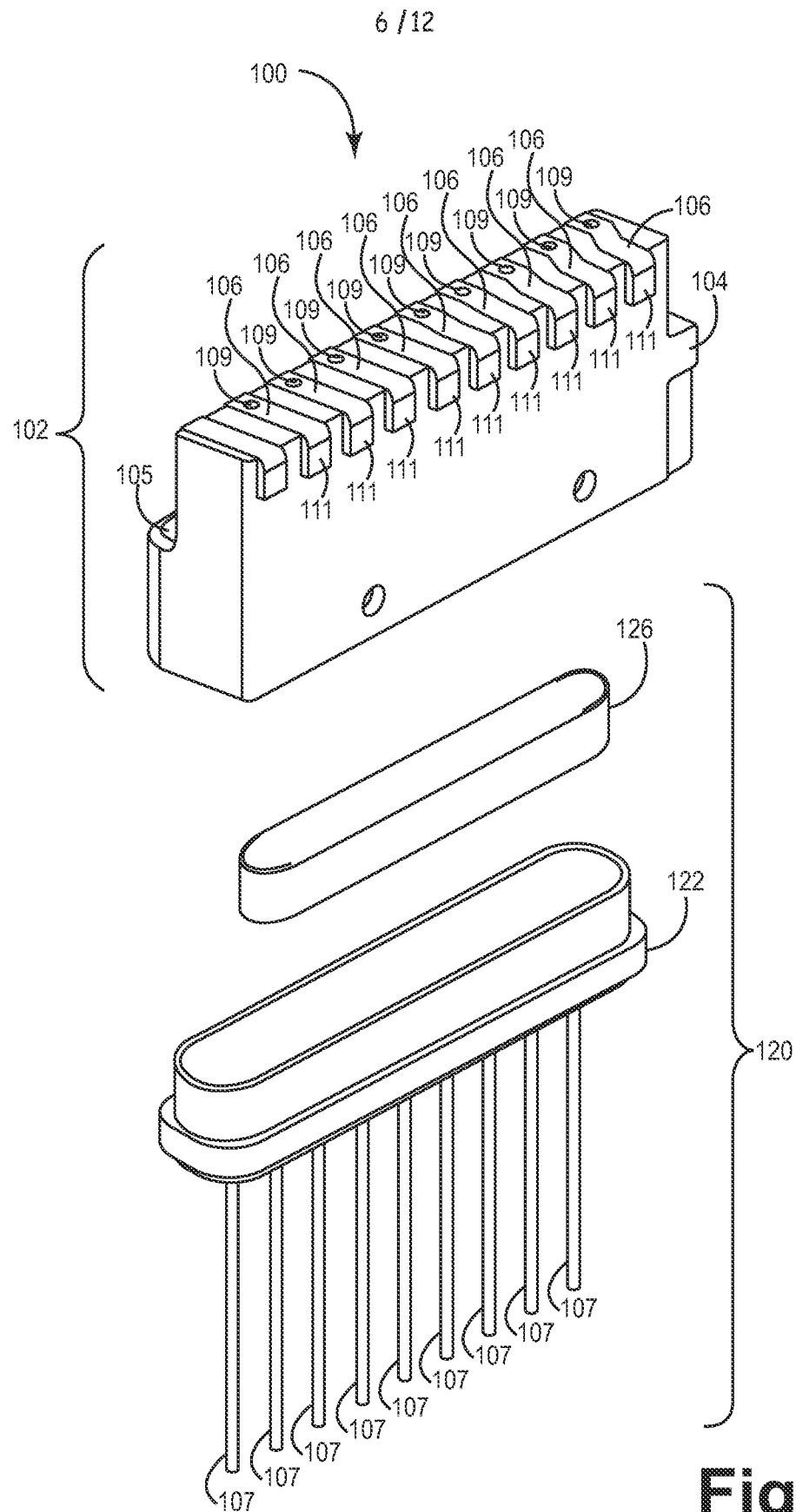


Fig. 3C



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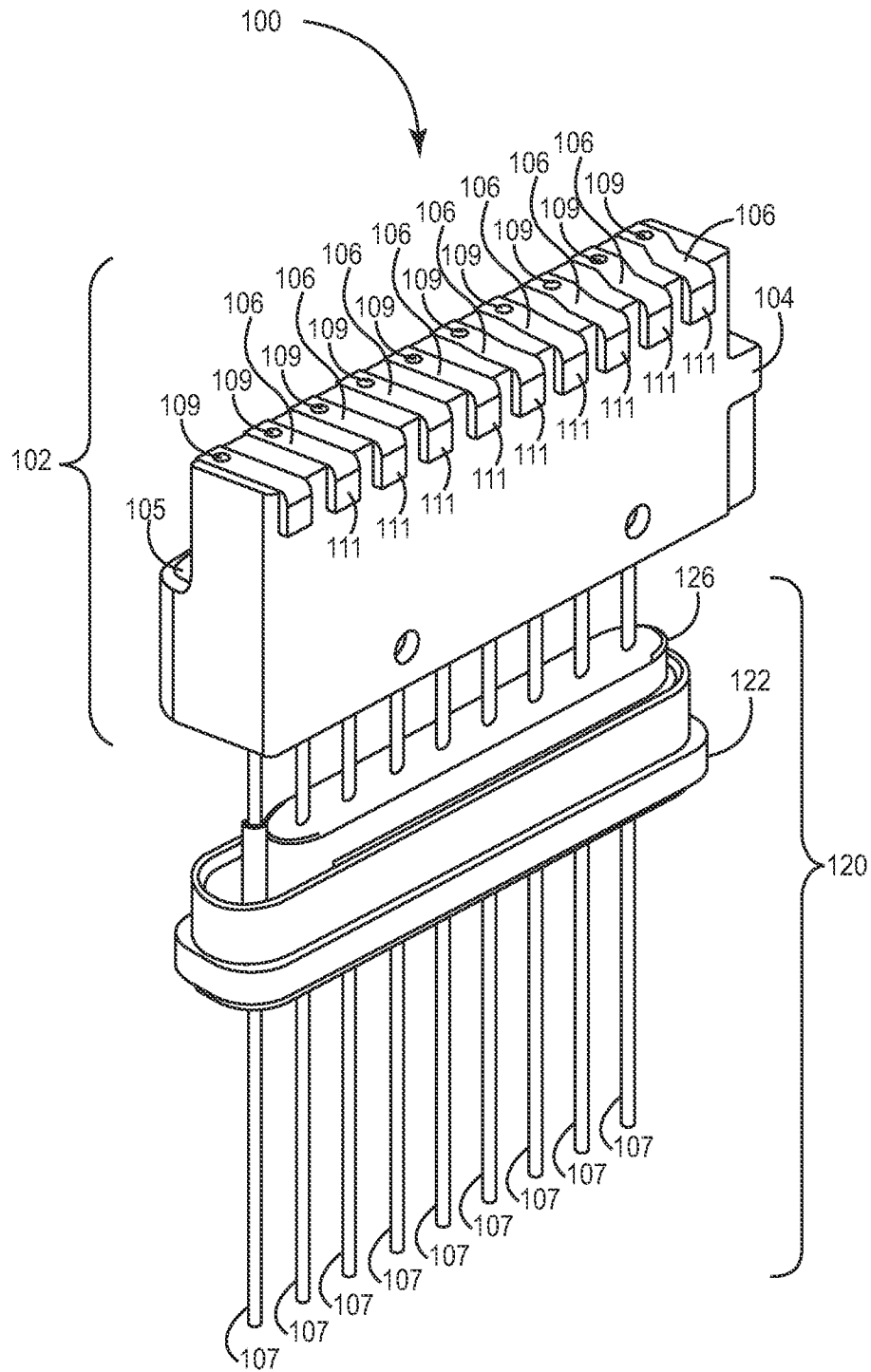
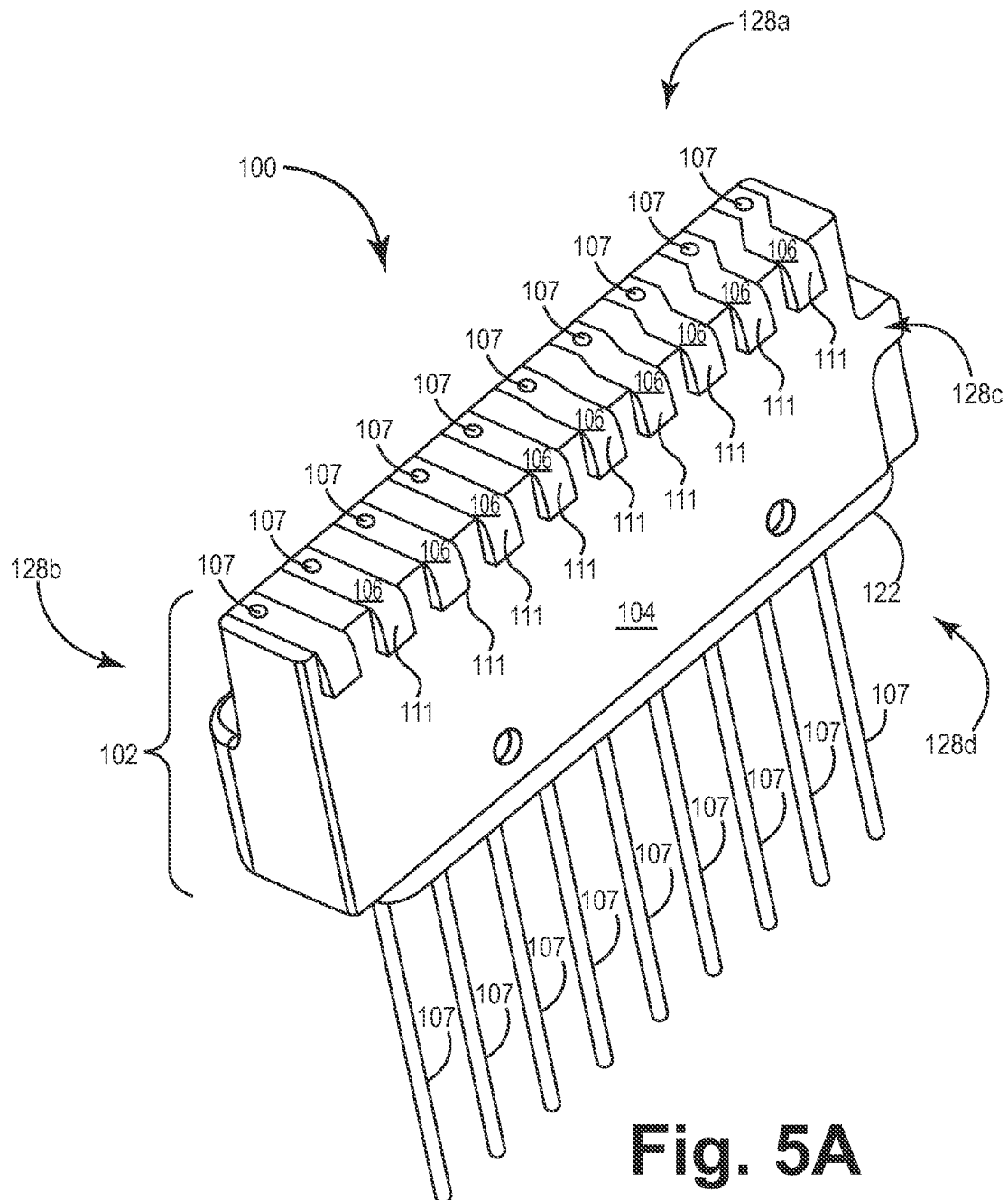
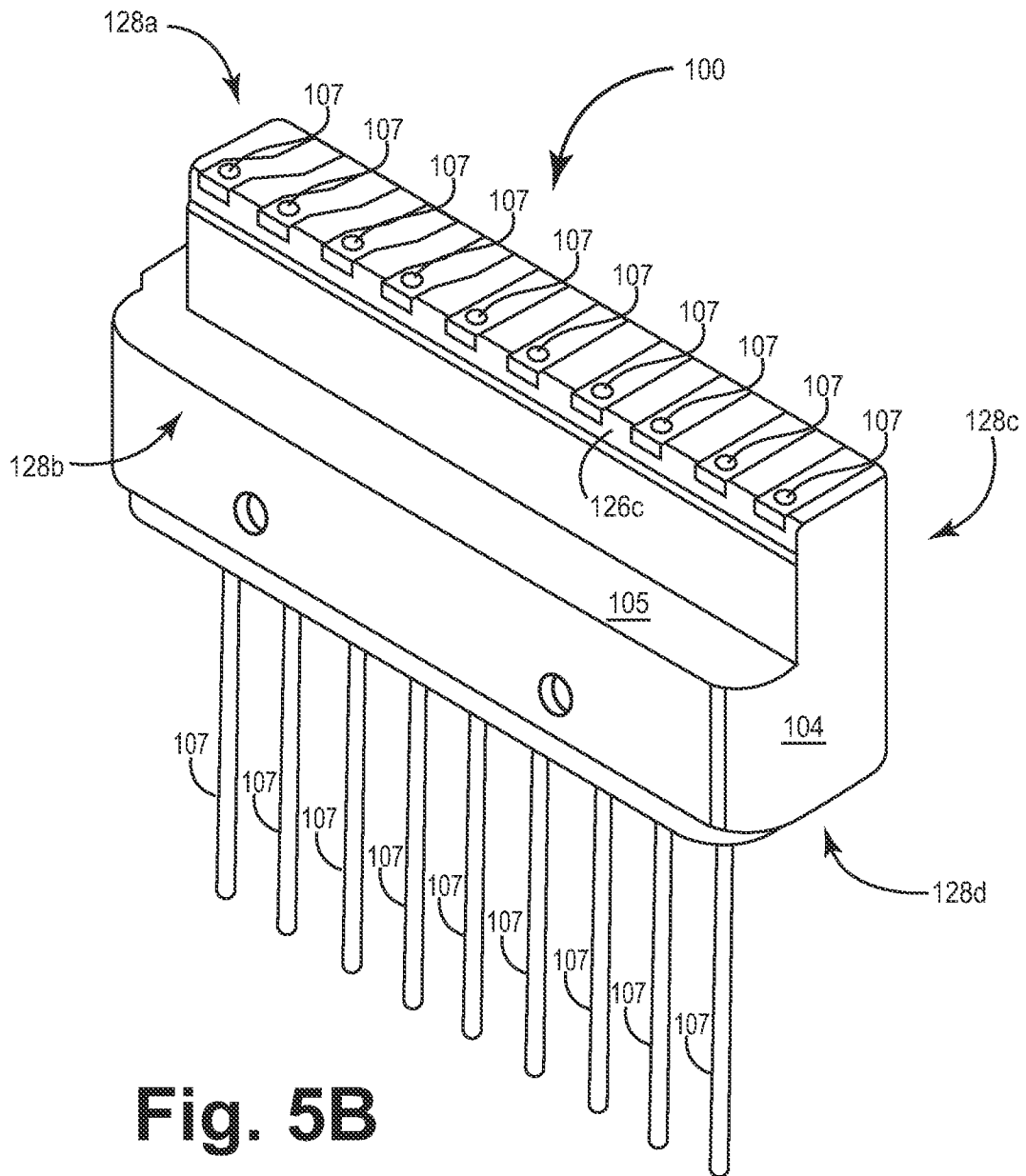


Fig. 4B

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**Fig. 5B**

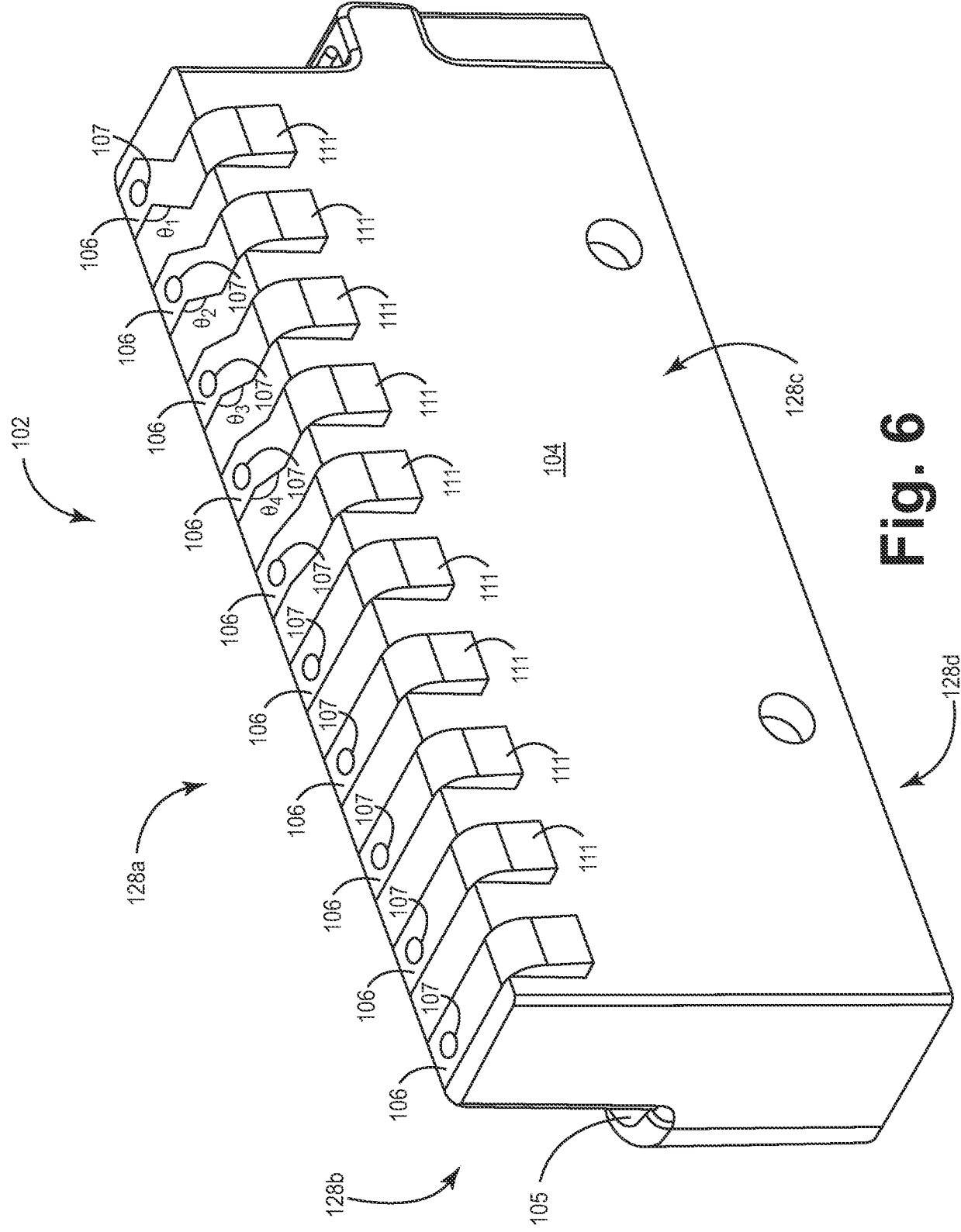


Fig. 6

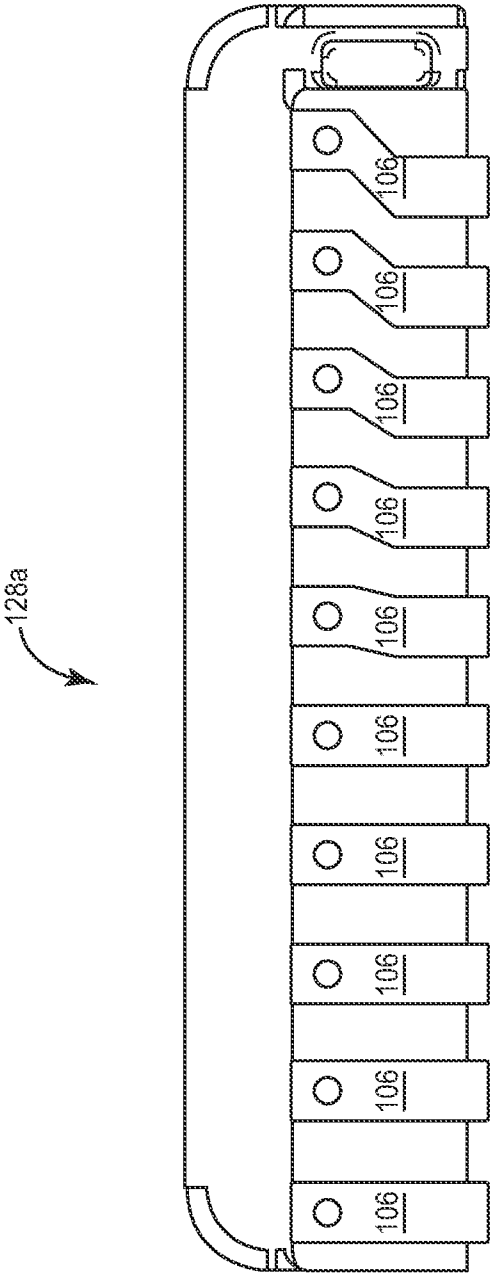
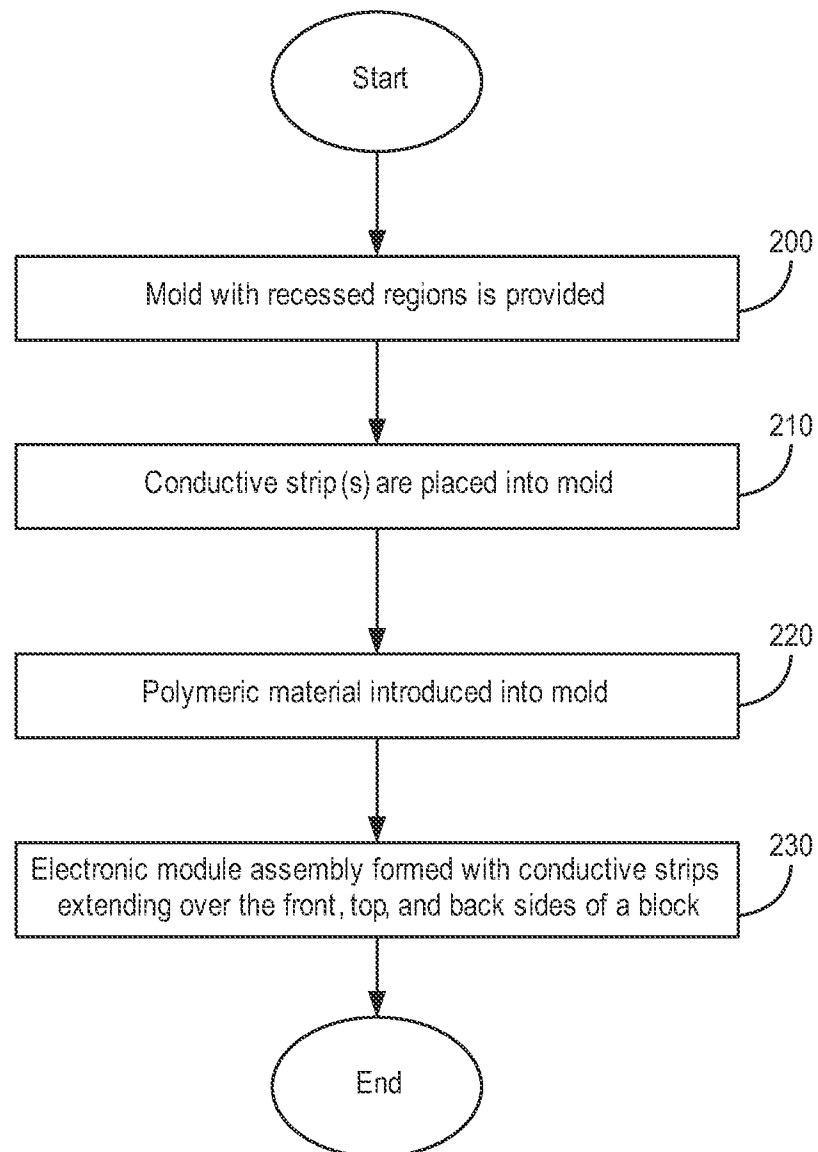


Fig. 7

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**Fig. 8**

INTERNATIONAL SEARCH REPORT

International application No

PCT/US2010/029345

A. CLASSIFICATION OF SUBJECT MATTER

INV. A61N1/375

ADD. H01B17/26 H01R13/52 H01G4/35

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

A61N

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2007/043399 A1 (STEVENSON ROBERT A [US] ET AL) 22 February 2007 (2007-02-22) paragraphs [0010], [0014], [0053] - [0081]; figures 1,9,28 -----	1-18
A	US 2007/179551 A1 (IYER RAJESH V [US] ET AL) 2 August 2007 (2007-08-02) the whole document -----	1-18
A	WO 2008/103166 A1 (WARSAW ORTHOPEDIC INC [US]; DERIDDER STEVEN D [US]; SIMONTON THOMAS A;) 28 August 2008 (2008-08-28) the whole document -----	1-18
A	WO 2007/087487 A1 (MEDTRONIC INC [US]; IYER RAJESH V [US]; KOCH DANIEL J [US]; GOLDMAN SI) 2 August 2007 (2007-08-02) the whole document -----	1-18



Further documents are listed in the continuation of Box C.



See patent family annex.

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Date of the actual completion of the international search

11 August 2010

Date of mailing of the international search report

24/08/2010

Name and mailing address of the ISA/

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Smit, Jos

INTERNATIONAL SEARCH REPORT

Information on patent family members

International application No

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Patent document cited in search report	Publication date	Patent family member(s)	Publication date
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